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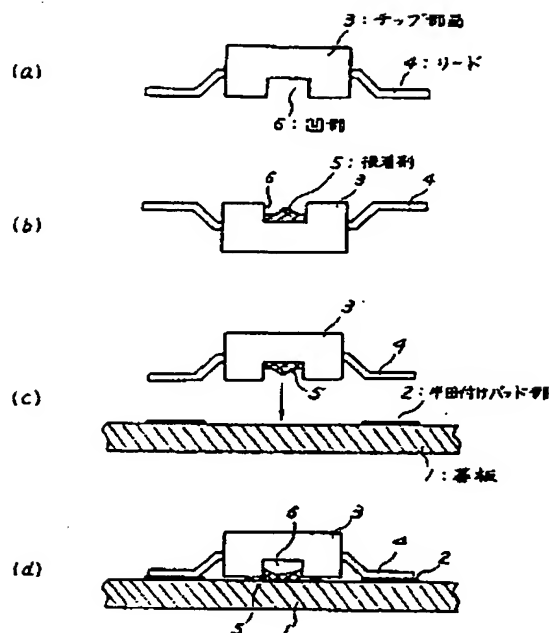
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TITLE : BONDING METHOD FOR CHIP PART



ABSTRACT : **PURPOSE:** To connect a chip part precisely onto a substrate by forming a recessed section to the back of the chip part, previously flowing adhesives into the recessed section and bonding the chip part with the substrate.

CONSTITUTION: A chip part 3, to the back thereof a recessed section 6 is shaped, is prepared. Adhesives 5 are flowed into the recessed section 6. The part 3 is turned over, and aligned with the predetermined position of a substrate 1. The part 3 is placed on the substrate 1. Consequently, adhesives 5 begin to flow out, and the part 3 is bonded onto the substrate 1. Excess adhesives are left in the recessed section 6 when adhesives 5 are surplus, and the whole adhesives 5 begin to flow out so as to contribute to bonding when adhesives 5 are little. Leads 4 for the part 3 are soldered. Accordingly, the chip part can be bonded with the substrate properly without being affected by the quantity of adhesives 5.

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